

Material Data Cards for Adhesives

- APPLUS+ RESCOLL BONDING DAYS 2025
- Daniel CAMPOS MURCIA / Maxime OLIVE









Applus+ Group

Applus+ is a global leader in inspection, testing and certification. Driven by our passion for progress and technological development, we'll keep moving towards a more sustainable future alongside our customers; re-enforcing our mission and company motto: **Together beyond standards.**



26,000+

People



€ 2,058M

Revenue



65+

Countries in all continents



Accredited

By main international entities



Energy & Industry Division

revenue



16,000+

personnel



Laboratories Division



€ 264N

revenue



2,589

personnel



Automotive Division



€ 392M

revenue



4,300

personnel



IDIADA Division



€ 331M

revenue

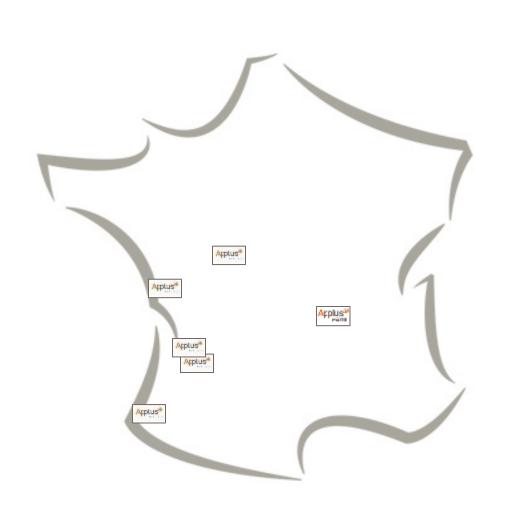


3,158
personnel









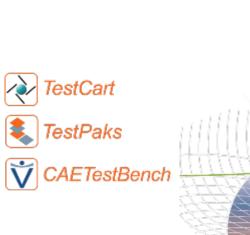
TESTING | **INNOVATION STUDIES** | **PRODUCTS**

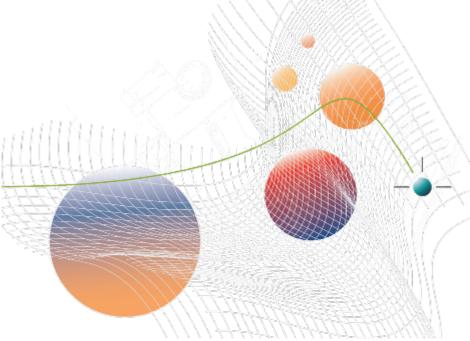


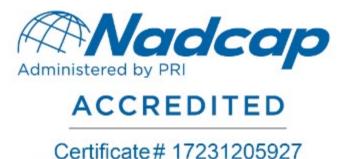












Non Metallic Materials Testing





OVERVIEW OF DATAPOINTLABS

Experience

- 30+ years of experience in materials testing and characterization
 - ISO 17025:2017 accredited, operating on an end-end digital platform
 - Nadcap accredited [Aerospace / Defense] (Metallic/Non-Metallic Materials Testing)

Operations

- Testing 2000+ materials per year
- Standard 5-day turnaround
- Comprehensive one-stop testing capability
 - +200 unique tests: all aspects of mechanical, thermal and rheological characterization

Capabilities

- Materials: plastics, composites, foam, rubber, metals, additive materials, films, adhesives
- May be characterized over a wide range of temperature and environmental conditions (elevated/cryogenic, heat aging, moisture conditioning, weathering, fluid exposure, in-vivo)
- Characterize non-linear and post-yield behavior, dynamic situations (drop, crash, impact),
 hyperelasticity (rubber, foams), time-based behavior (creep, stress relaxation, viscoelasticity)

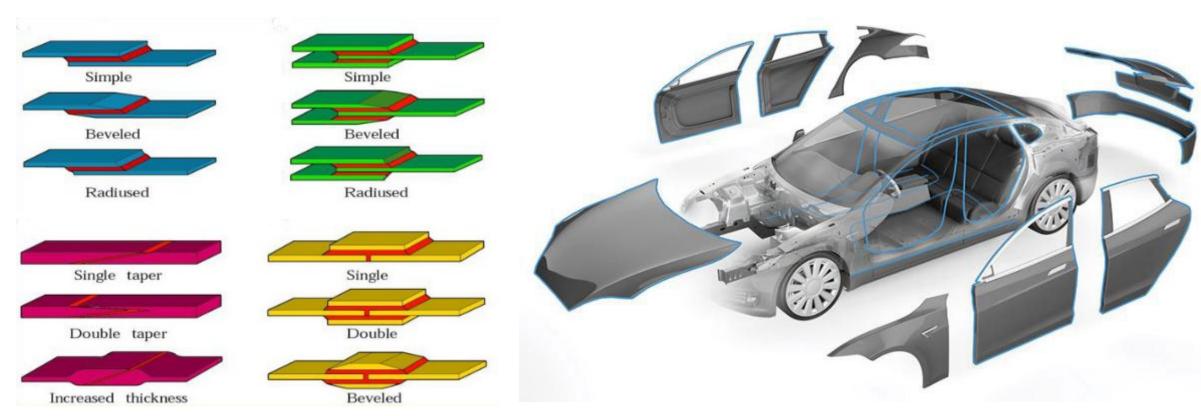


Widespread use of structural adhesives in more critical applications

Prediction of adhesive performance is mandatory but associated with high design costs and cycle time ...

Finite Element Analysis (FEA) emerged as a great solution to

- Model the adhesive and assembly in various conditions
- Reduce design cycle time and optimize joint design with limited numbers of experiments



Source: Adhesives.org



Simulation implies to feed the model with data

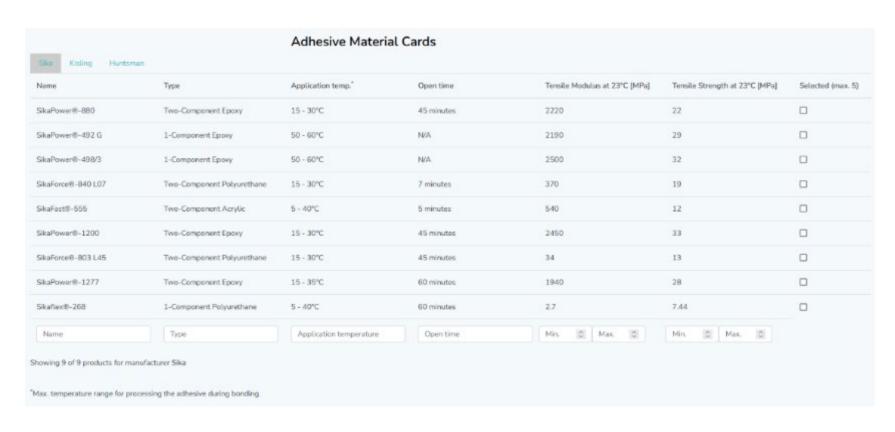
Definition of set of tests or test packages to build the data set Realization of tests in various configurations, different loading modes

Examples of such data sets available for commercial adhesives... can be seen as extended technical data sheets

These data set can be used to run simple design calculations eg CALCBOND

Data sets representative of standard lab conditions:

- substrates
- thickness
- curing
- •



Source : Calchond



In addition, bonding is a multimaterial technology

Low thickness joints and interfaces must be considered with suitable models

Damage and failure propagation must be also addressed in the models

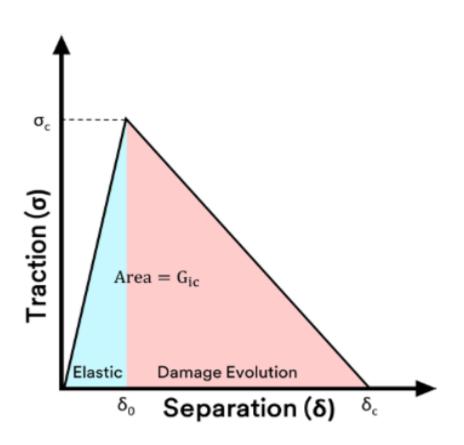
-> Introduction of Cohesive Zone Models

Need for bond simulation with up-to-date models

With data from tests on samples as close to real life

Available in a plug and play format

... ready to import in your favorite FEA software



Source: 3M

Physical Effect	Test Name	Test Sketch	Material Parameter	Description	Symbol	Unit
Elasticity	Uniaxial Tension Test	A PARTIE AND A PAR	Young's Modulus and Poisson's Ratio	Resistance to elastic deformation and transverse contraction in tension	E_1, E_{11}, K_{111}	MPa
Damage Initiation	Thick Adherend Butt Joint Tension Test	A. T. C.	Tensile Strength	Maximum stress in laterally constrained tension	σ_{I}	MPa
	Thick Adherend Shear Test		Shear Strength	Maximum stress in shear	$\sigma_{\rm H} = \sigma_{\rm H}$	MPa
Damage Evolution	Tapered Double Cantilever Beam (TDCB) Test		Mode Fracture Energy (Critical Energy Release Rate)	Resistance to crack propagation in Mode I (opening mode)	$G_{\rm IC}$	$\frac{N}{mm} = \frac{k!}{m^2}$
	End-Notehod Flexure (ENF) Test		Mode II Fracture Energy (Critical Energy Release Rate)	Resistance to crack propagation in Mode II (shear mode)	$G_{\rm HC} = G_{\rm HEC}$	$\frac{N}{mm} = \frac{k!}{m^2}$



TestCart

Comprehensive online catalog and order system for +200 unique tests characterizing physical, thermal and flow properties of materials for use in R&D and product development metals, plastics, composites, rubber, foam, rubber, films

TestPaks®

Material testing and material parameter conversion to generate +180 material cards for 36 simulation (CAE) programs, including finite-element analysis, crash and drop-test simulations, injection-molding and other process simulations

CAETestBench™

Validate your simulation against a physical part, created and tested using a rigid protocol, which can be accurately replicated in your solver – probe simulation accuracy and quantify its ability to replicate the test Validations range from simple modes to tensile more complex, multi-axial modes, impact and failure









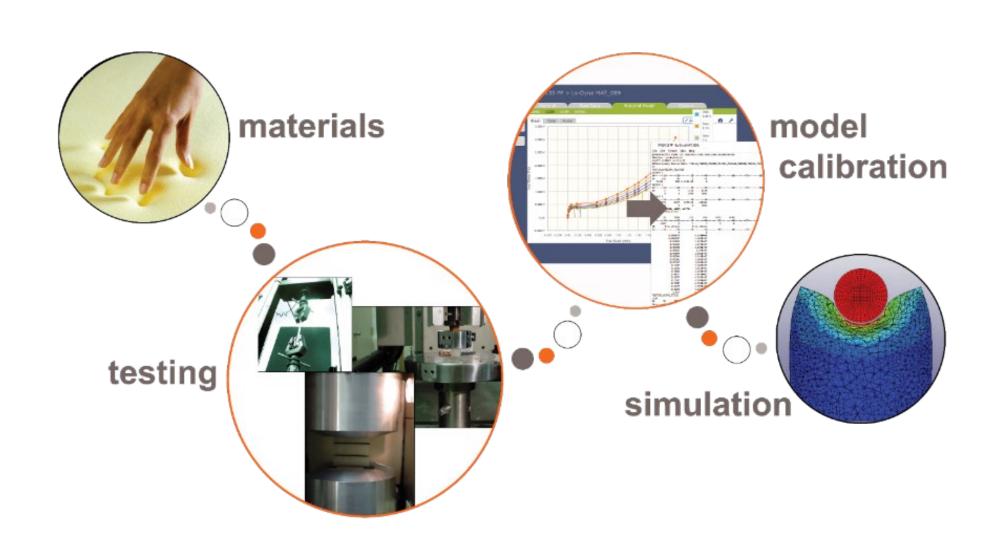
"from expert materials testing to CAE-ready material cards"

Material properties for your CAE

- What is included?
 - Specific material testing for CAE material model requirements
 - Conversion of raw test data to material model parameters
 - Solver-formatted, CAE-ready material file
 - Material card validation (Optional)

Universal TestPak available for some common material models

- What do they consist of?
 - Single set of material tests; material files for multiple CAE solvers
 - Particularly attractive for material suppliers serving OEM customers requiring data for CAE

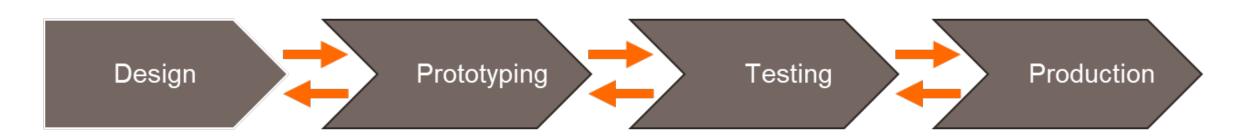




New product development means new materials

- Traditional prototyping is
 - Iterative
 - Time-Consuming
 - Costly
 - Resource-Intensive

Traditional product development process (multiple physical iterations)



CAE-driven product development process (multiple virtual iterations)

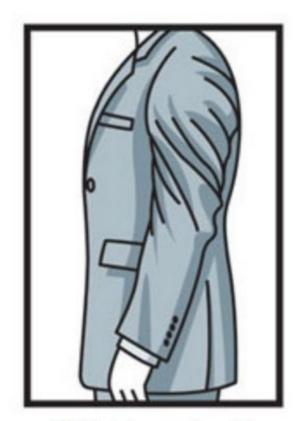


Our digital services can simplify and improve this transition, reducing the number of physical prototypes thanks to the accurate material models and digital twins.



The importance of using the Right Material Card

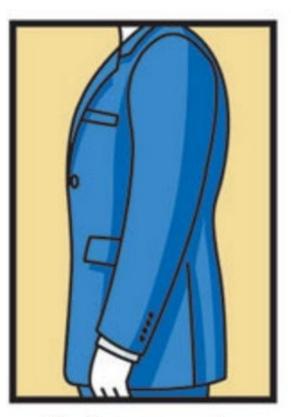
Standard "Off-the-shelf" Material Card



Off the shelf

- Material to be calibrated may be similar but not identical to the standard, reducing simulation accuracy
- Test data from textbooks or standardized tests lose relevance outside their contexts
- Standard models usually can't be transferred to other software or adjusted for different simulations settings

Tailor-made Material Card

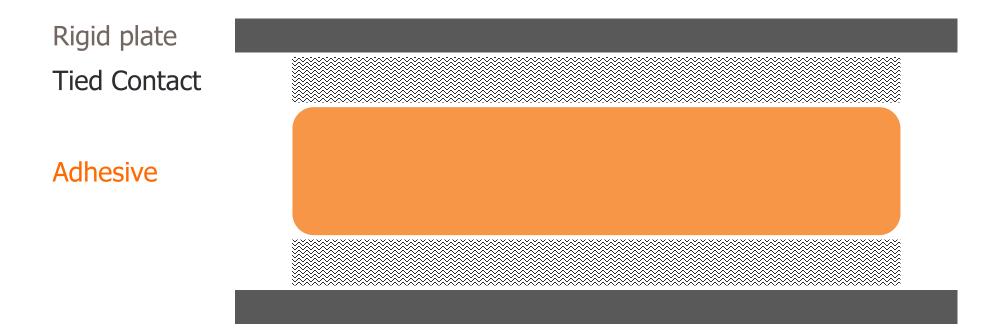


Tailor-made

- Each material is distinct, with properties influenced by both the material and forming conditions
- Test data come from specialized tests tailored to the application, covering factors like temperature, humidity, strain rate, and material orientation
- Material cards are calibrated for specific software and simulation settings, including non-physical parameters

The material cards are the foundation upon which the simulation is built. A proper material card is necessary to ensure success





1. Adhesive model + Rigid substrate + Tied connection

- Simple to calibrate
- Good accuracy of the adhesive behavior
- Failure within the adhesive

2. Adhesive model + Substrate model + Tied connection

- More complex to calibrate
- More testing needed
- Better accuracy on the prediction of the union behavior
- Failure withing the adhesive or the substrate

3. Adhesive model + Substrate model + Cohesive zone model

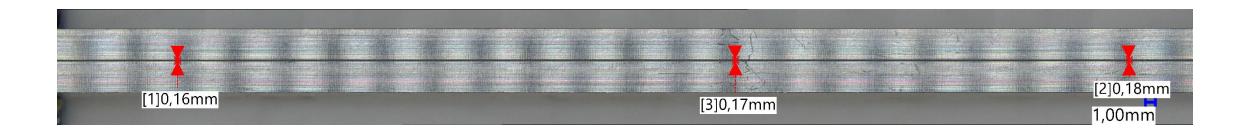
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TESTING

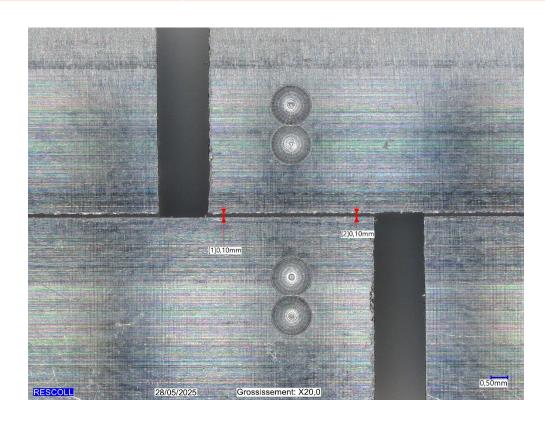
Materials

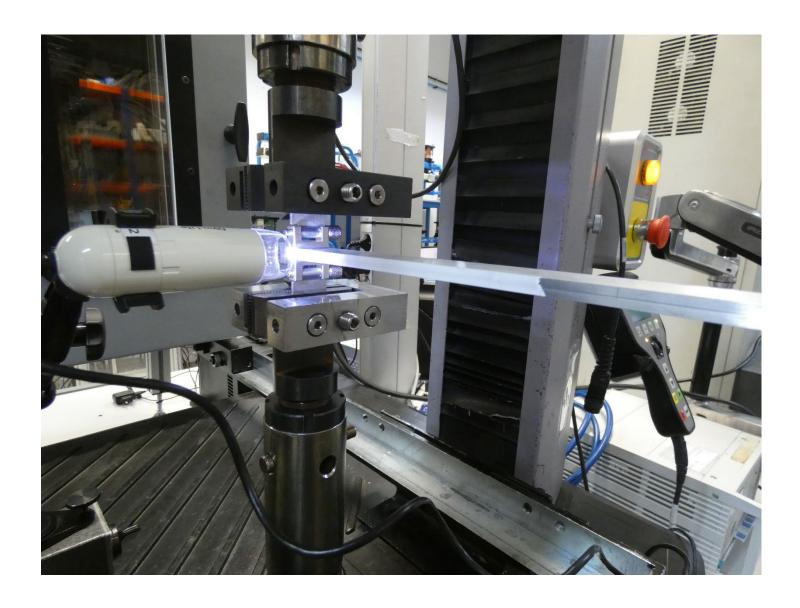
- Al 2024 sandblasted, degreased and etched
- 3M Scotch Weld 3901 Metal Primer
- 3M Scotch Weld 2216 (flexible 2K epoxy)



Test Plan

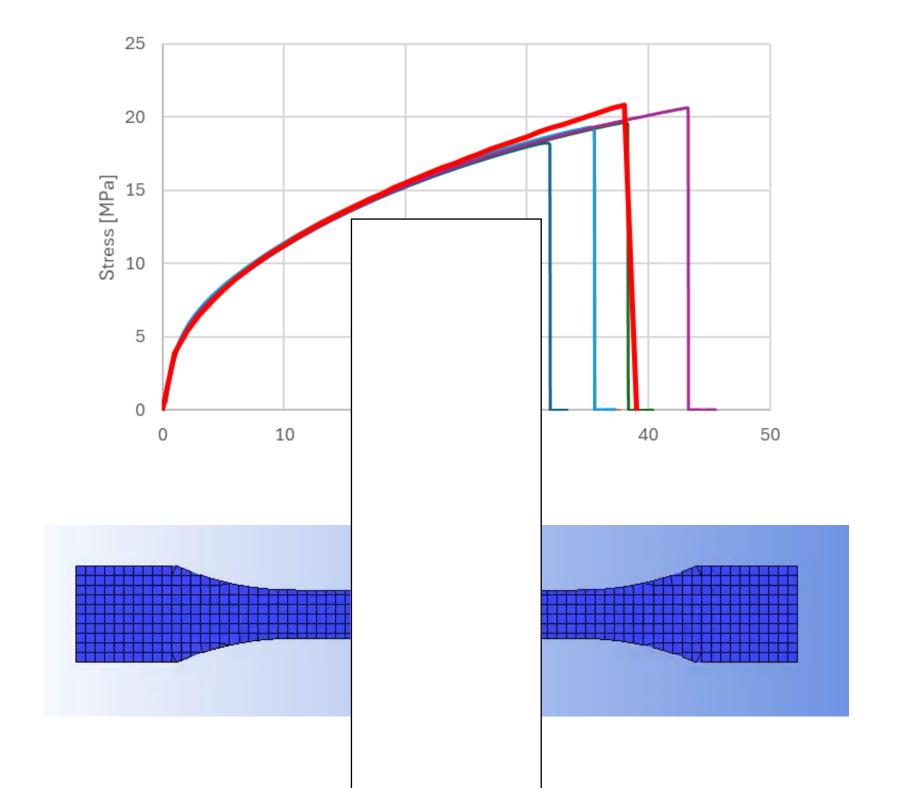
Test	Standard
Bulk tensile	ISO 527-2
Thick adherend shear test (TAST)	ISO 11003-2
Mode 1 fracture toughness	EN 6033



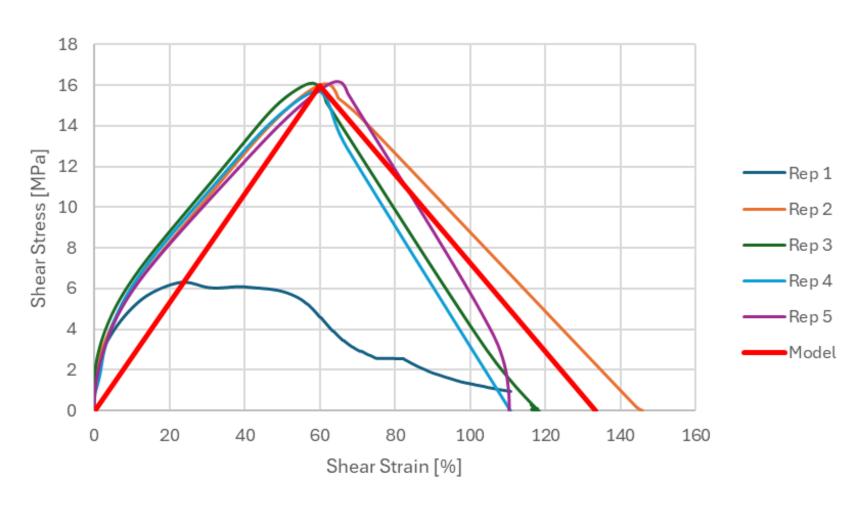




Bulk Material

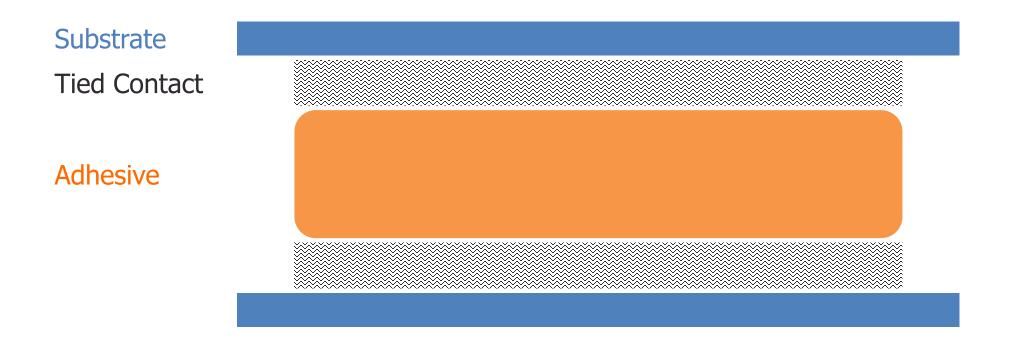


Bonded Union – TAST CLOSED UP









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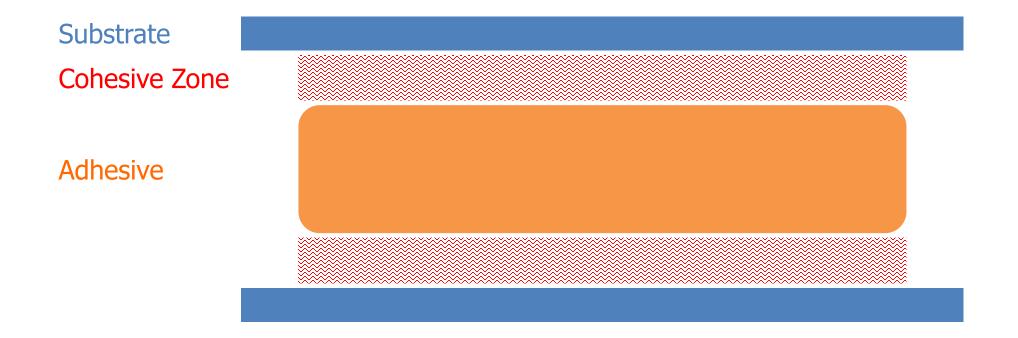
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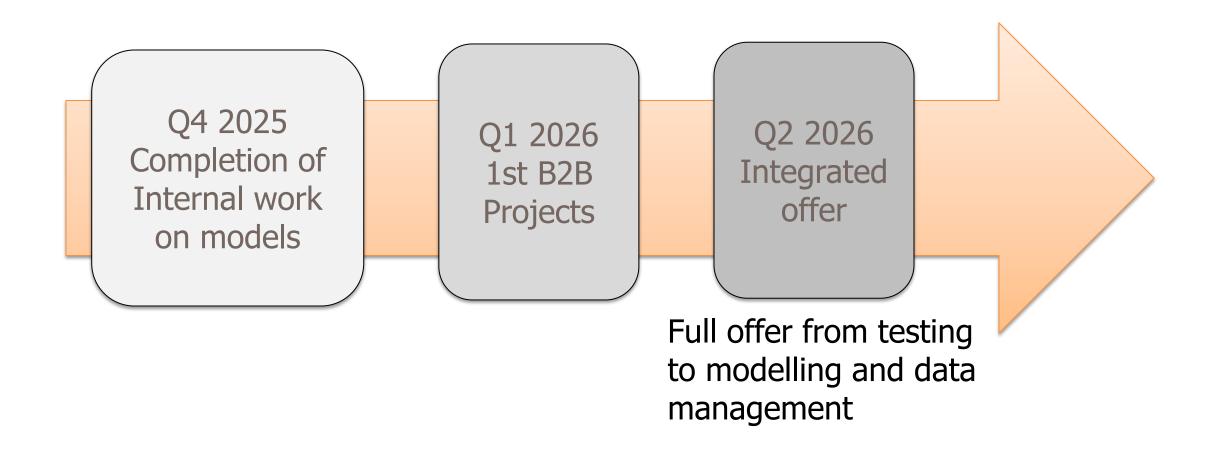
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Adhesive model Roadmap: next steps



Let's start working together, share your needs and applications!

Thanks! Applus Applu

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